





140V PNP MEDIUM POWER TRANSISTOR PowerDI[®]5

Features

- 43% smaller than SOT223; 60% smaller than TO252
- Maximum height just 1.1mm
- Rated up to 3.2W
- $V_{CEO} = -140V$
- $I_C = -4A$; $I_{CM} = -10A$
- Low Saturation voltage
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 1)
- "Green" Device (Note 2)

Features

SLIC DC-DC converter

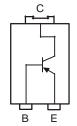
Mechanical Data

- Case: PowerDI®5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.093 grams (approximate)









Top View

Bottom View

Device Schematic

Pin-out diagram

Ordering Information (Note 3)

Part Number	Case	Packaging
DXT2014P5-13	PowerDI [®] 5	5000/Tape & Reel

- 1. No purposefully added lead. Halogen and Antimony Free.
- 2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com
- 3. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



DXT2014 = Product Type Marking Code Oll = Manufacturers' Code Marking K = Factory Designator YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 09 for 2009) WW = Week code (01 to 53)





Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-180	V
Collector-Emitter Voltage	V_{CEO}	-140	V
Emitter-Base Voltage	V_{EBO}	-7	V
Continuous Collector Current	lc	-4	A
Peak Pulse Current	I _{CM}	-10	A

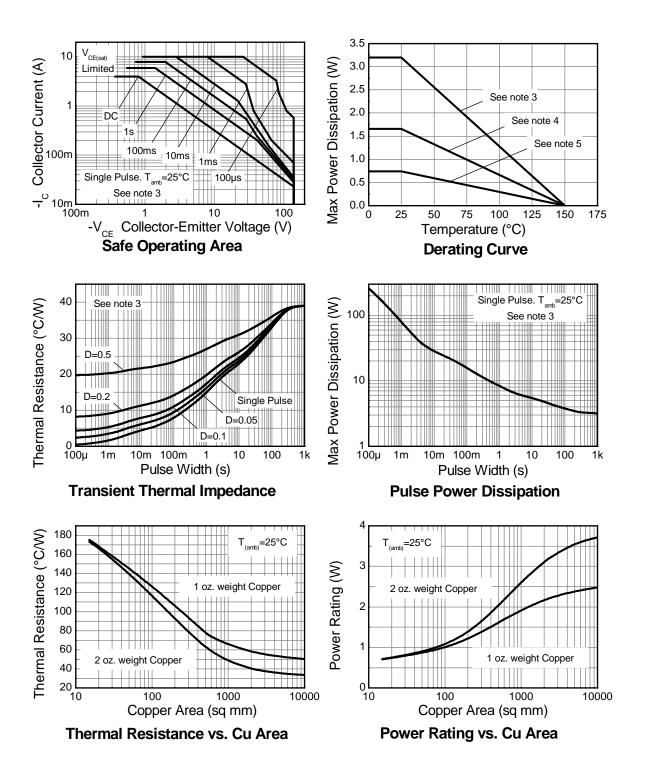
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation @ T _A = 25°C (Note 4)	P_{D}	3.2	W
Thermal Resistance, Junction to Ambient Air (Note 4) @T _A = 25°C	$R_{ heta JA}$	39	°C/W
Power Dissipation @ T _A = 25°C (Note 5)	P_{D}	1.7	W
Thermal Resistance, Junction to Ambient Air (Note 5) @T _A = 25°C	$R_{ heta JA}$	75	°C/W
Power Dissipation @ T _A = 25°C (Note 6)	P_{D}	0.74	W
Thermal Resistance, Junction to Ambient Air (Note 6) @T _A = 25°C	$R_{ heta JA}$	169	°C/W
Thermal Resistance, Junction to Collector Terminal	$R_{ heta JT}$	5.6	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Notes:

- 4. Device mounted on FR-4 PCB, single sided 2 oz. copper, collector pad dimensions 50mm x 50mm.
- 5. Device mounted on FR-4 PCB, single sided 1 oz. copper, collector pad dimensions 25mm x 25mm.
- 6. Device mounted on FR-4 PCB, single sided 1 oz. copper, minimum recommended pad layout.









Electrical Characteristics @TA = 25°C unless otherwise specified

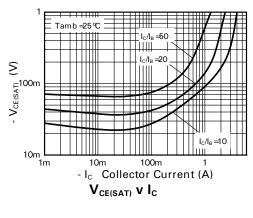
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-180	-200	_	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 7)	V _{(BR)CEO}	-140	-160		V	$I_C = -10 \text{mA}$
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	-7.0	-8.0		٧	$I_E = -100 \mu A$
Collector Cutoff Current	I _{CBO}		<1 —	-20 -0.5	nA μA	$V_{CB} = -150V$ $V_{CB} = -150V$, $T_{amb} = 100 ^{\circ}C$
Collector Cutoff Current	I _{CER} R≤1kΩ		<1 —	-20 -0.5	nA μA	V _{CB} = -150V V _{CB} = -150V, T _{amb} = 100 °C
Emitter Cutoff Current	I _{EBO}	_	<1	-10	nA	V _{EB} = -6V
Collector-Emitter Saturation Voltage (Note 7)	V _{CE(sat)}		-40 -55 -85 -275	-60 -80 -120 -360	mV	I _C = -0.1A, I _B = -5mA I _C = -0.5A, I _B = -50mA I _C = -1A, I _B = -100mA I _C = -3A, I _B = -300mA
Base-Emitter Saturation Voltage (Note 7)	V _{BE(sat)}		-940	-1040	mV	$I_C = -3A$, $I_B = -300mA$
Base-Emitter Turn-On Voltage (Note 7)	V _{BE(on)}		-830	-930	mV	$V_{CE} = -5V, I_{C} = -3A$
DC Current Gain (Note 7)	h _{FE}	100 100 45 —	225 200 100 5	300 — —		V _{CE} = -5V, I _C = -10mA V _{CE} = -5V, I _C = -1A V _{CE} = -5V, I _C = -3A V _{CE} = -5V, I _C = -10A
Transition Frequency	f _T		120		MHz	$V_{CE} = -10V, I_{C} = -100mA,$ f = 50MHz
Output Capacitance	C _{obo}		33	_	pF	V _{CB} = -10V, f = 1MHz
Switching Times	t _{on} t _{off}		42 636		ns ns	$V_{CC} = -50V, I_C = 1A,$ $I_{B1} = -I_{B2} = -100mA$

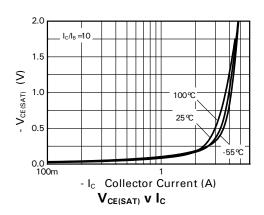
Notes: 7. Pulse Test: Pulse width $\leq 300 \mu s$. Duty cycle $\leq 2.0\%$.

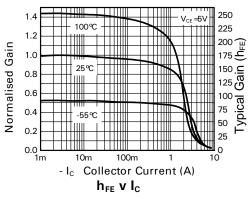


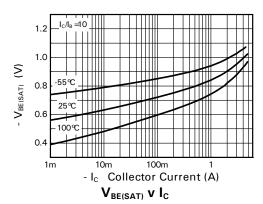


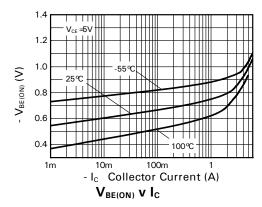
Typical Characteristic







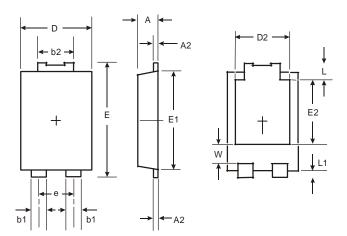






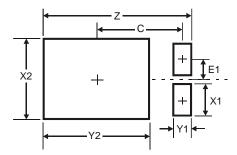


Package Outline Dimensions



PowerDI [®] 5					
Dim	Min	Max			
Α	1.05	1.15			
A2	0.33	0.43			
b1	0.80	0.99			
b2	1.70	1.88			
D	3.90	4.05			
D2	3.054 Typ				
Е	6.40	6.60			
е	1.84	Тур			
E1	5.30	5.45			
E2	3.549 Typ				
L	0.75	0.95			
L1	0.50	0.65			
W	1.10	1.41			
All Di	All Dimensions in mm				

Suggested Pad Layout



Dimensions	Value (in mm)
Z	6.6
X1	1.4
X2	3.6
Y1	0.8
Y2	4.7
С	3.87
F1	0.9





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